

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application. Please amend claim 1 and add new claim 22:

LISTING OF CLAIMS:

1. (Currently Amended) An electronic apparatus comprising:
 - an electronic circuit board;
 - an electrically conductive casing for encasing said electronic circuit board;
 - a semiconductor element module having lead terminals electrically connected to said electronic circuit board ~~via a plurality of lead terminals~~, said semiconductor element module having a column-shaped section, an axis of said column-shaped section being parallel to a direction of extension of said lead terminals; and
 - a resin fixture intervening between said electrically conductive casing and said semiconductor element module, said resin fixture mounted with said semiconductor element module ~~and fitted to said electrically conductive casing~~, said resin fixture having a cylinder-shaped section for retaining, in its inner periphery, said column-shaped section of said semiconductor element module, a surface of an outer periphery and end surface of said cylinder-shaped section being plated and ~~an a surface of said~~ inner periphery ~~surface~~ of said cylinder-shaped section not being plated, and
 - said resin fixture, on another side of said cylinder-shaped section, directly fitted to said electrically conductive casing.

2. (Canceled)

3. (Canceled)

4. (Original) An electronic apparatus according to claim 1, wherein
said semiconductor element module has a raised portion formed on its outer
surface at a site where said semiconductor element module is fitted to said resin fixture,
and wherein

said resin fixture has a recessed portion formed in its inner surface at a site
where said semiconductor module is mounted, said recessed portion being fitted to said
raised portion.

5. (Original) An electronic apparatus according to claim 1, wherein
said semiconductor element module has an externally threaded portion
formed on its outer surface at a site where said semiconductor element module is fitted to
said resin fixture, and wherein

said resin fixture has an internally threaded portion formed in its inner
surface at a site where said semiconductor module is mounted, said externally threaded
portion being screwed into said internally threaded portion.

6. (Original) An electronic apparatus according to claim 1, wherein
said semiconductor element module has a recessed portion formed in its
outer surface at a site where said semiconductor element module is fitted to said resin
fixture, and wherein
said resin fixture has a raised portion formed on its inner surface at a site
where said semiconductor module is mounted, said raised portion being fitted to said
recessed portion.
7. (Canceled)
8. (Original) An electronic apparatus according to claim 1, wherein
said electronic circuit board is bonded to and encased in said electrically
conductive casing by use of an electrically conductive adhesive sheet.
9. (Canceled)
10. (Original) An electronic apparatus according to claim 1, wherein
said semiconductor element module has a raised portion formed on its outer
surface at a site where said semiconductor element module is fitted to said resin fixture,
and wherein

said resin fixture has a notched portion formed in its outer wall and has a recessed portion formed in the inner surface at a site where said semiconductor module is mounted, said recessed portion being fitted to said raised portion, and wherein

said electrically conductive casing has a hooked portion which fits said notched portion of said resin fixture.

11. (Original) An electronic apparatus according to claim 1, wherein

said semiconductor element module has an externally threaded portion formed on its outer surface at a site where said semiconductor element module is fitted to said resin fixture, and wherein

said resin fixture has a notched portion formed in its outer wall and has an internally threaded portion formed in its inner surface at a site where said semiconductor module is mounted, said externally threaded portion being screwed into said internally threaded portion, and wherein

said electrically conductive casing has a hooked portion which fits said notched portion of said resin fixture.

12. (Original) An electronic apparatus according to claim 1, wherein

said semiconductor element module has a recessed portion formed in its outer surface at a site where said semiconductor element module is fitted to said resin fixture, and wherein

said resin fixture has a notched portion formed in its outer wall and has a raised portion formed on its inner surface at a site where said semiconductor module is mounted, said raised portion being fitted to said recessed portion, and wherein

said electrically conductive casing has a hooked portion which fits said notched portion of said resin fixture.

13. (Original) An electronic apparatus according to claim 1, wherein

said semiconductor element module has a raised portion formed on its outer surface at a site where said semiconductor element module is fitted to said resin fixture, and wherein

said resin fixture has a protrusion formed on its outer surface and has a recessed portion formed in its inner surface at a site where said semiconductor module is mounted, said recessed portion being fitted to said raised portion, and wherein

said electrically conductive casing has an insertion hole which receives said protrusion of said resin fixture.

14. (Original) An electronic apparatus according to claim 1, wherein

said semiconductor element module has an externally threaded portion formed on its outer surface at a site where said semiconductor element module is fitted to said resin fixture, and wherein

said resin fixture has a protrusion formed on its outer surface and has an internally threaded portion formed in its inner surface at a site where said semiconductor module is mounted, said externally threaded portion being screwed into said internally threaded portion, and wherein

said electrically conductive casing has an insertion hole which receives said protrusion of said resin fixture.

15. (Original) An electronic apparatus according to claim 1, wherein

said semiconductor element module has a recessed portion formed in its outer surface at a site where said semiconductor element module is fitted to said resin fixture, and wherein

said resin fixture has a protrusion formed on its outer surface and has a raised portion formed on its inner surface at a site where said semiconductor module is mounted, said raised portion being fitted to said recessed portion, and wherein

said electrically conductive casing has an insertion hole which receives said protrusion of said resin fixture.

16. (Canceled)

17. (Canceled)

18. (Canceled)

19. (Canceled)

20. (Canceled)

21. (Previously Presented) An electronic apparatus comprising:

an electronic circuit board;

an electrically conductive casing for encasing said electronic circuit board;

a coaxial optical semiconductor element module electrically connected to said electronic circuit board via a plurality of lead terminals, said semiconductor element module having a column-shaped section, an axis of said column-shaped being parallel to a direction of extension of said lead terminals; and

a resin fixture intervening between said electrically conductive casing and said semiconductor element module, said resin fixture mounted with said semiconductor element module and fitted to said electrically conductive casing, said resin fixture having an opening having an inner diameter which is larger than an outer diameter of said column-shaped section of said semiconductor element module, said opening retaining said column-shaped section therein, an outer periphery surface of said resin fixture being metal plated and an inside surface of said opening not being metal plated.

22. (New) The electronic apparatus according to claim 1, wherein the resin fixture has a heat insulating property with respect to the heat generated by the electronic circuit board.